

Inventor(s): UMENO, Kuniharu et al.
Appl. No.: To Be Assigned
Title: Resin Composition for Encapsulating Semiconductor Chip
and Semiconductor Device Therewith
Filing Date: Concurrent Herewith
Atty. Dkt. No.: 033036.075 Page: 1 of 1

1 / 1

Fig.1

